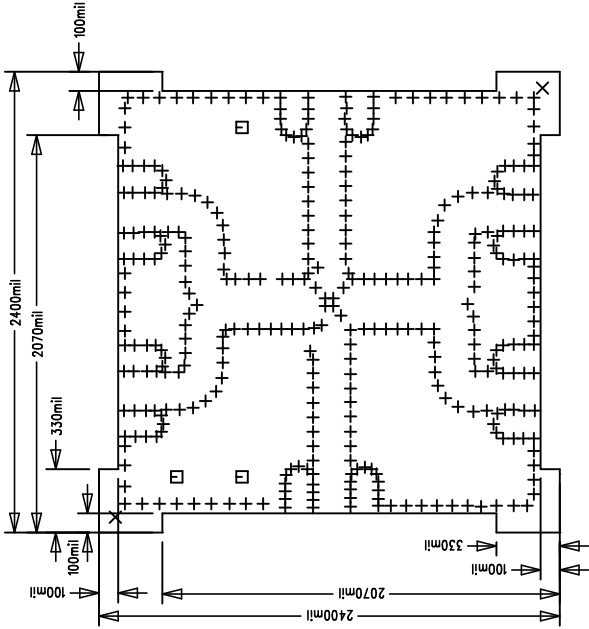
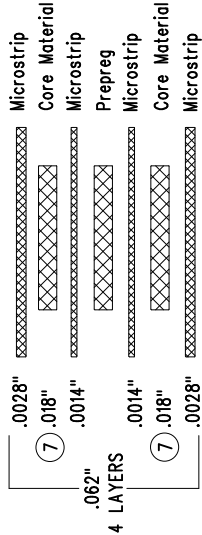


REVISIONS		
REV	DESCRIPTION	APPR
A	PROTOTYPE RELEASE	



Component Side (Layer1)

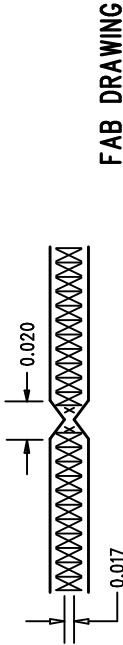
SIZE	QTY	SYM	PLTD	TOL
10	340	+	YES	+/-0.003
70	2	X	NO	+/-0.003
94	3	□	YES	+/-0.003




NOTES : Unless Otherwise Specified

1. MATERIAL: EPOXY FIBERGLASS, NEMA GRADE FR-4. 1 OZ. COPPER ON INTERNAL LAYER. 2 OZ. COPPER ON OUTER LAYER.
THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS
2. DRILLING: DRILL HOLES PER SCHEDULE. PLATE THROUGH HOLES WITH COPPER, .001 INCH THICK MIN. ALL HOLE SIZES ARE SPECIFIED AFTER PLATING.
HOLE LOCATION TOLERANCES ARE +/- .003 INCH IN RELATION TO CENTER
3. SOLDER MASK : SMOBC BOTH SIDES USING GREEN LPI.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK
5. FINISH: WHITE TIN IMMERSION (OMIKRON) BOTH SIDES.
OR LEAD FREE SOLDER
6. CONTROLLED 50 OHM IMPEDANCE (AT 6 GHz FREQ.) FOR LAYER 1-2 AND LAYER 4-3.
7. SUBJECT TO CHANGE BY MANUFACTURER, DEPENDING ON DIELECTRIC CONSTANT DEVIATIONS. PLEASE CONSULT LTC.

8. SCORING



FAB DRAWING

APPROVALS		 LINEAR TECHNOLOGY 1630 McCarthy Blvd. Milpitas, CA 95035 PH: (408)432-1900	
DRAWN	INIT	DATE	
CHECK			
DESIGN	Antonina K		
ENGR	Doug S.		
TITLE: LT5568EUF-2 I/Q Modulator with Current BB Interface 700-1050MHz			
SIZE	A	DC1178A	REV. A
SCALE = NONE		DES-260044	
		SHT 1 of 1	